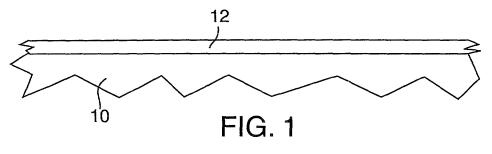
Title: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING RUTHENIUM AND TUNGSTEN CONTAINING LAYERS Express Mail: EL 874430976 US

Mailed: October 29, 2001 Attorney Matter No. 6047-61466



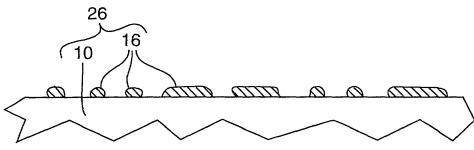


FIG. 2

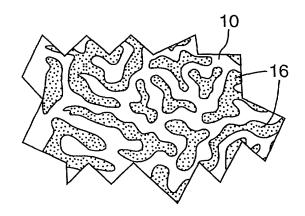
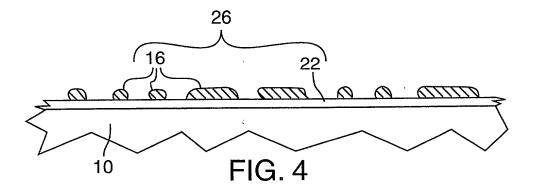


FIG. 3

Title: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING RUTHENIUM AND TUNGSTEN CONTAINING LAYERS Express Mail: EL 874430976 US Mailed: October 29, 2001

Attorney Matter No. 6047-61466



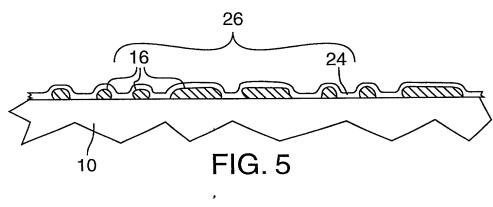


FIG. 6

FIG. 7

Title: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING RUTHENIUM AND TUNGSTEN CONTAINING LAYERS Express Mail: EL 874430976 US Mailed: October 29, 2001 Attorney Matter No. 6047-61466

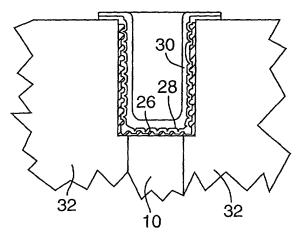


FIG. 8A

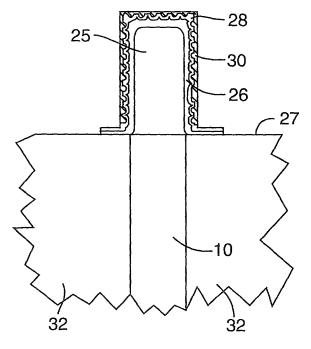


FIG. 8B

Title: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING RUTHENIUM AND TUNGSTEN CONTAINING LAYERS Express Mail: EL 874430976 US Mailed: October 29, 2001 Attorney Matter No. 6047-61466

